9. (Amended) A resin seal process of a semiconductor device as set forth in claim 7 [or 8], wherein a plurality of said through openings and said resin flow passages are provided for performing filling of the resin at a plurality of portions.

14. (Amended) A resin seal process of a semiconductor device as set forth in claim 7 [or 8], wherein filling of said resin is performed through one or more through holes provided in said wired substrate for electrical connection.

15. (Amended) A resin seal process of a semiconductor device as set forth in claim 7 [or 8], which comprises step of setting a plurality of molding objects within the mold and clamping said mold for filing said resin for a plurality of semiconductor chips simultaneously.

18. (Amended) A resin sealing apparatus as set forth in claim 16 [or 17], wherein said mold is consisted of an upper die, an intermediate die and a lower die[,]];

said lower die has a cavity portion as a die for outer shape of a molded resin portion of said semiconductor device;

said intermediate die is exchangeably arranged a gate plate formed with a resin injection conduit as a hole formed through a position corresponding to said through opening;

said upper die is formed with a runner as a groove extending to a position corresponding to said resin injection conduit; and

said resin flow passage is formed with said resin injection conduit and said runner.

19. (Amended) A resin sealing apparatus as set forth in claim 16 [or 17], wherein said resin flow passage is formed to a position corresponding to a through hole provided in said wired substrate for electrical connection.

20. (Amended) A resin sealing apparatus as set forth in claim 16 [or 17], wherein said mold is formed with a stepped down portion recessed with a tilted peripheral portion of said cavity portion in a region corresponding to the semiconductor chip.